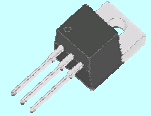


Supplier: Fagor Electrónica S. Coop

Package: TO-220AB



Part Number:

Description: SCR's and Triacs

COMPOSITION PART	MATERIAL NAME	MATERIAL MASS( mg)	MATERIAL MASS( %)	ELEMENT NAME COMPOSITION	CAS N°	ELEMENT % ( BY WEIGHT)	Cd (ppm)	Pb (ppm)	Hg (ppm)	Cr 6+ (ppm)	PBBs (ppm)	PBDEs (ppm)
LEAD FRAME	Cu alloy	557,380	29,27%	Ni Cu Fe P	7440-02-0 7440-50-8 7439-89-6 7723-14-0	99,87 0,1 0,03	< 2	< 2	< 2	< 2	< 5	< 5
ENCAPSULATION	Epoxy	1258,800	66,11%	Fused silica Polyglycidyl Ether O-cresol Formaldehyde Novolac Brominated Epoxy resin Antimony oxide Carbon black	60676-86-0 29690-82-2 40039-93-8 1309-64-4 1333-86-4	70-75 10-15 1-3 1-3 1-3	< 2	< 2	< 2	< 2	< 5	< 5
CHIP	Doped Silicon Glass Passivated	7,350	0,39%	Si Al Ni SiO2 PbO Al2O3	7440-213 7429-90-5 7440-02-0 7631-86-9 1317-36-8 1344-28-1	90,7-92,1 1,7-2,2 0,8-1,2 2,7-2,9 2,5-2,7 0,2-0,3	< 2	46962 (**)	< 2	< 2	< 5	< 5
DIE BONDING MATERIAL	Solder Wire	12,980	0,68%	Pb Sn Ag	7489-92-1 7440-31-5 7440-22-4	95 2,5 2,5	< 2	921700 (*)	< 2	< 2	< 5	< 5
WIRES	Aluminum	3,170	0,17%	Al	7429-90-5	100	< 2	< 2	< 2	< 2	< 5	< 5
COATING	Sn	64,520	3,39%	Sn	7440-31-5	100	< 2	< 2	< 2	< 2	< 5	< 5
WHOLE ITEM		1904,200	100,00%									

Exception according to annex of Directive 2002/95/EC (RoHS):

\* Lead in high melting temperature type solders (i.e. tin-lead solder alloys containing more than 85% lead)

\*\* Lead in glass of cathode ray tubes, electronic componentes and fluorescent tubes

